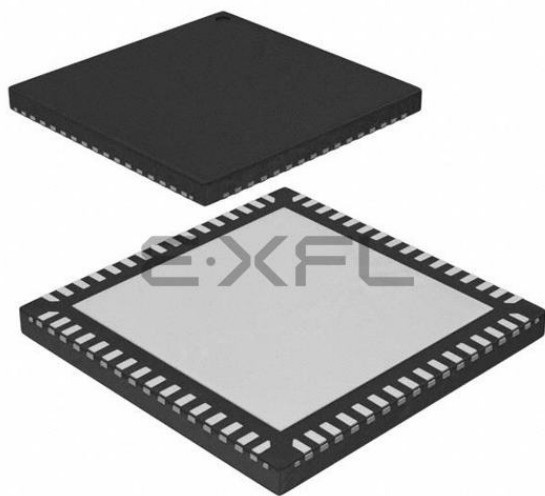




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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	52
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 20x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsamd20j14a-mu

- Up to five 16-bit Timer/Counters (TC), configurable as either:
 - One 16-bit TC with two compare/capture channels
 - One 8-bit TC with two compare/capture channels
 - One 32-bit TC with two compare/capture channels, by using two TCs
- 32-bit Real Time Counter (RTC) with clock/calendar function
- Watchdog Timer (WDT)
- CRC-32 generator
- Up to six Serial Communication Interfaces (SERCOM), each configurable to operate as either:
 - USART with full-duplex and single-wire half-duplex configuration
 - Inter-Integrated Circuit (I²C) up to 400kHz
 - Serial Peripheral Interface (SPI)
- One 12-bit, 350ksps Analog-to-Digital Converter (ADC) with up to 20 channels
 - Differential and single-ended input
 - 1/2x to 16x programmable gain stage
 - Automatic offset and gain error compensation
 - Oversampling and decimation in hardware to support 13-, 14-, 15- or 16-bit resolution
- 10-bit, 350ksps Digital-to-Analog Converter (DAC)
- Two Analog Comparators (AC) with window compare function
- Peripheral Touch Controller (PTC)
 - 256-Channel capacitive touch and proximity sensing
- I/O
 - Up to 52 programmable I/O pins
- Packages
 - 64-pin TQFP, QFN
 - 64-ball UFBGA
 - 48-pin TQFP, QFN
 - 45-ball WLCSP
 - 32-pin TQFP, QFN
- Operating Voltage
 - 1.62V – 3.63V
- Power Consumption
 - Down to 70µA/MHz in active mode
 - Down to 8µA running the Peripheral Touch Controller

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3.2. SAM D20G

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD20G14A-AU	16K	2K	TQFP32	Tray
ATSAMD20G14A-AUT				Tape & Reel
ATSAMD20G14A-AN				Tray
ATSAMD20G14A-ANT				Tape & Reel
ATSAMD20G14A-MU			QFN32	Tray
ATSAMD20G14A-MUT				Tape & Reel
ATSAMD20G14A-MN				Tray
ATSAMD20G14A-MNT				Tape & Reel
ATSAMD20G15A-AU	32K	4K	TQFP48	Tray
ATSAMD20G15A-AUT				Tape & Reel
ATSAMD20G15A-AN				Tray
ATSAMD20G15A-ANT				Tape & Reel
ATSAMD20G15A-MU			QFN48	Tray
ATSAMD20G15A-MUT				Tape & Reel
ATSAMD20G15A-MN				Tray
ATSAMD20G15A-MNT				Tape & Reel
ATSAMD20G16A-AU	64K	8K	TQFP48	Tray
ATSAMD20G16A-AUT				Tape & Reel
ATSAMD20G16A-AN				Tray
ATSAMD20G16A-ANT				Tape & Reel
ATSAMD20G16A-MU			QFN48	Tray
ATSAMD20G16A-MUT				Tape & Reel
ATSAMD20G16A-MN				Tray
ATSAMD20G16A-MNT				Tape & Reel

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD20J18A-AU	256K	32K	TQFP64	Tray
ATSAMD20J18A-AUT				Tape & Reel
ATSAMD20J18A-AN				Tray
ATSAMD20J18A-ANT				Tape & Reel
ATSAMD20J18A-MU			QFN64	Tray
ATSAMD20J18A-MUT				Tape & Reel
ATSAMD20J18A-MN				Tray
ATSAMD20J18A-MNT				Tape & Reel
ATSAMD20J18A-CU			UFBGA64	Tray
ATSAMD20J18A-CUT				Tape & Reel

3.4. Device Identification

The DSU - Device Service Unit peripheral provides the Device Selection bits in the Device Identification register (DID.DEVSEL) in order to identify the device by software. The device variants have a reset value of DID=0x1001drxx, with the LSB identifying the die number ('d'), the die revision ('r') and the device selection ('xx').

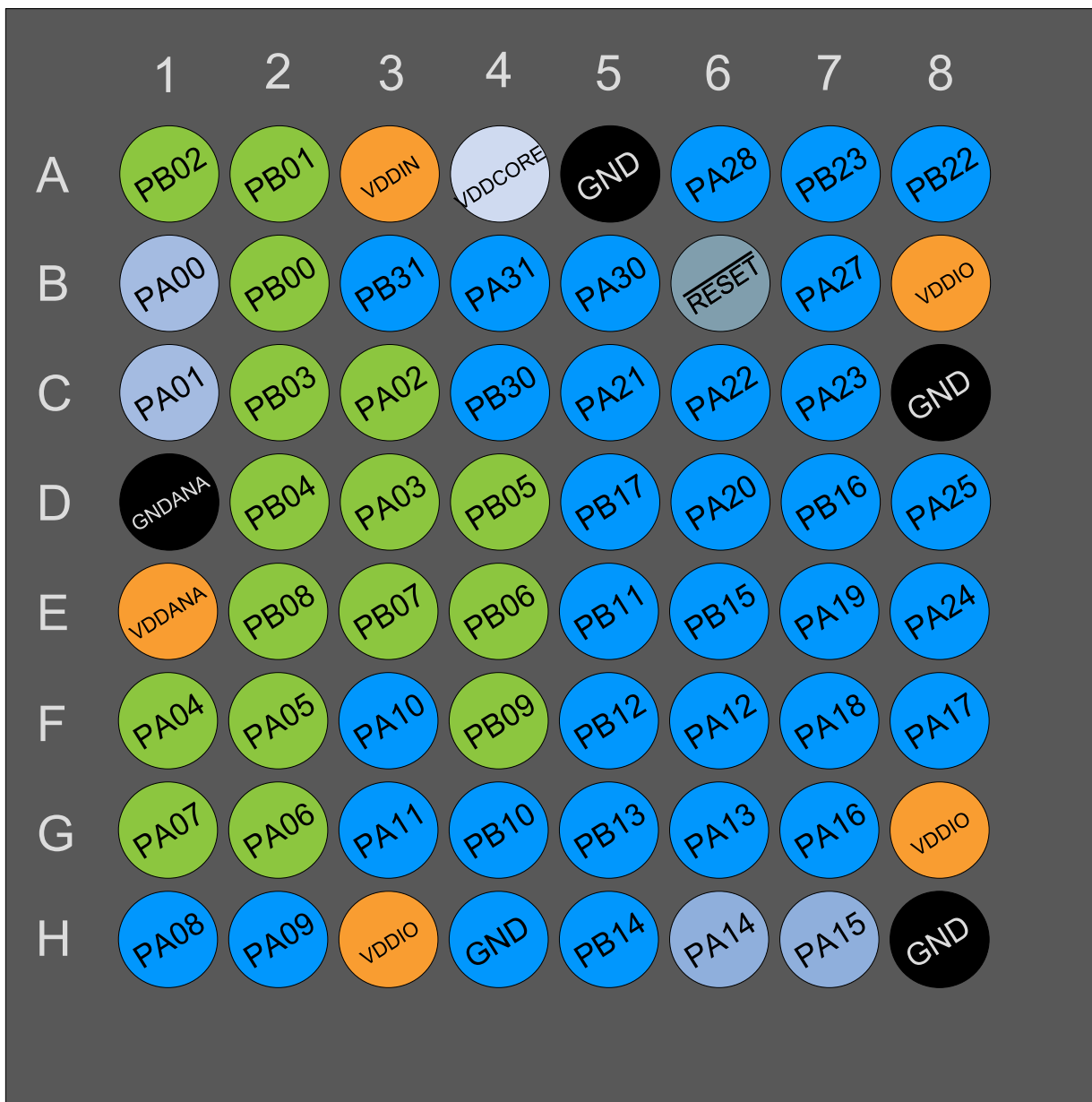
Table 3-1. Device Identification Values

Device Variant	DID.DEVSEL	Device ID (DID)
SAMD20J18C	0x00	0x10001300
SAMD20J18A	0x00	0x10001300
SAMD20J17A	0x01	0x10001301
SAMD20J16A	0x02	0x10001302
SAMD20J15A	0x03	0x10001303
SAMD20J14A	0x04	0x10001304
SAMD20G18A	0x05	0x10001305
SAMD20G17A	0x06	0x10001306
SAMD20G16A	0x07	0x10001307
SAMD20G15A	0x08	0x10001308
SAMD20G14A	0x09	0x10001309
SAMD20E18A	0x0A	0x1000130A
SAMD20E17A	0x0B	0x1000130B
SAMD20E16A	0x0C	0x1000130C
SAMD20E15A	0x0D	0x1000130D

Device Variant	DID.DEVSEL	Device ID (DID)
SAMD20E14A	0x0E	0x1000130E
Reserved	0x0F	
SAMD20G18U	0x10	0x10001310
SAMD20G17U	0x11	0x10001311
Reserved	0x12 - 0xFF	

Note: The device variant (last letter of the ordering number) is independent of the die revision (DSU.DID.REVISION): The device variant denotes functional differences, whereas the die revision marks evolution of the die. The device variant denotes functional differences, whereas the die revision marks evolution of the die.

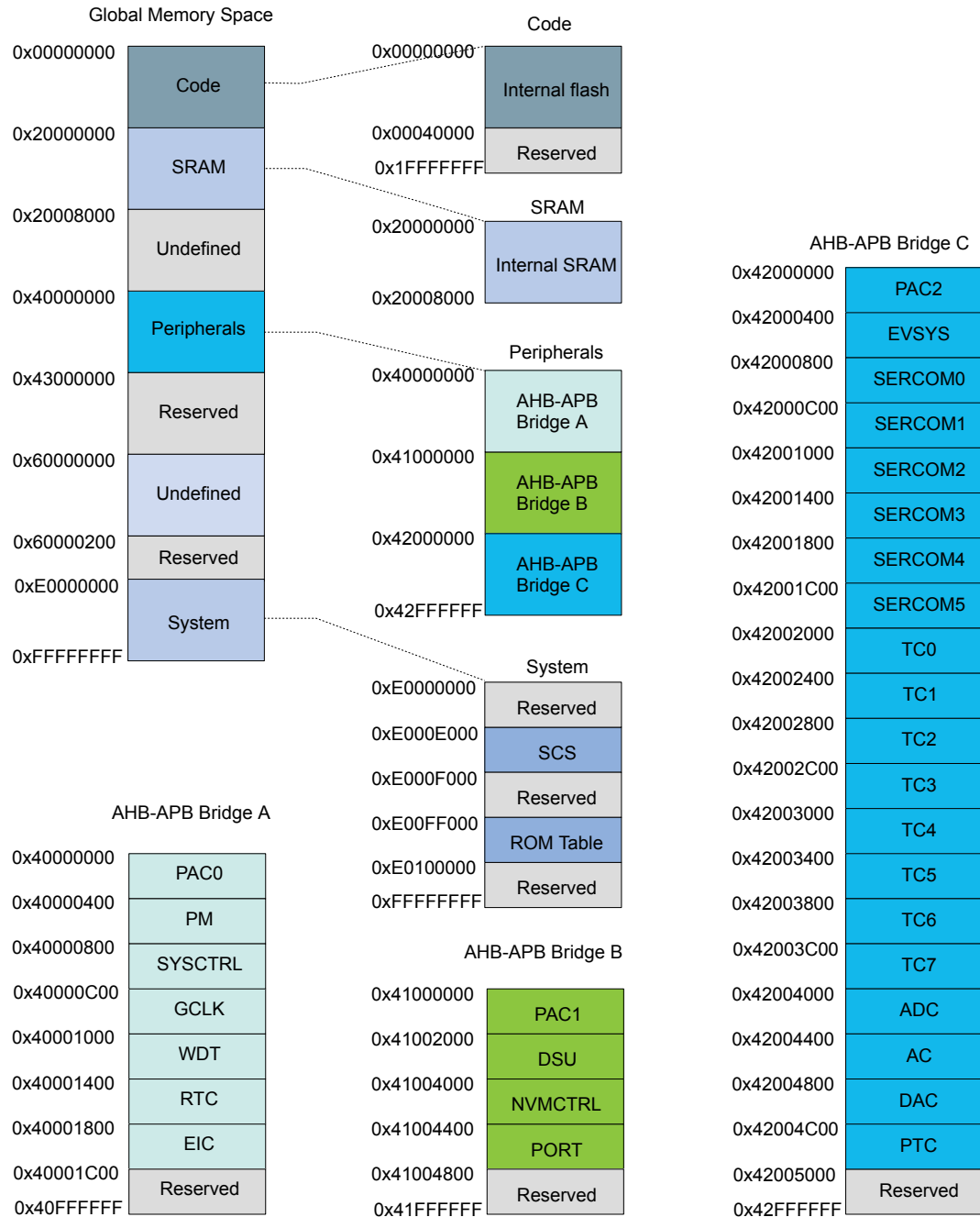
5.1.2. UFBGA64



- DIGITAL PIN
- ANALOG PIN
- OSCILLATOR
- GROUND
- INPUT SUPPLY
- REGULATED OUTPUT SUPPLY
- RESET PIN

6. Product Mapping

Figure 6-1. Product Mapping



This figure represents the full configuration of the SAM D20 device with maximum flash and SRAM capabilities and a full set of peripherals. Refer to the [Configuration Summary](#) for details.

(INTFLAG) register. The interrupt flag is set when the interrupt condition occurs. Each interrupt in the peripheral can be individually enabled by writing a one to the corresponding bit in the peripheral's Interrupt Enable Set (INTENSET) register, and disabled by writing a one to the corresponding bit in the peripheral's Interrupt Enable Clear (INTENCLR) register. An interrupt request is generated from the peripheral when the interrupt flag is set and the corresponding interrupt is enabled. The interrupt requests for one peripheral are ORed together on system level, generating one interrupt request for each peripheral. An interrupt request will set the corresponding interrupt pending bit in the NVIC interrupt pending registers (SETPEND/CLRPEND bits in ISPR/ICPR). For the NVIC to activate the interrupt, it must be enabled in the NVIC interrupt enable register (SETENA/CLRENA bits in ISER/ICER). The NVIC interrupt priority registers IPR0-IPR7 provide a priority field for each interrupt.

Table 7-3. Interrupt Line Mapping

Peripheral Source	NVIC Line
EIC NMI – External Interrupt Controller	NMI
PM – Power Manager	0
SYSCTRL – System Control	1
WDT – Watchdog Timer	2
RTC – Real Time Counter	3
EIC – External Interrupt Controller	4
NVMCTRL – Non-Volatile Memory Controller	5
EVSYS – Event System	6
SERCOM0 – Serial Communication Interface 0	7
SERCOM1 – Serial Communication Interface 1	8
SERCOM2 – Serial Communication Interface 2	9
SERCOM3 – Serial Communication Interface 3	10
SERCOM4 – Serial Communication Interface 4	11
SERCOM5 – Serial Communication Interface 5	12
TC0 – Timer Counter 0	13
TC1 – Timer Counter 1	14
TC2 – Timer Counter 2	15
TC3 – Timer Counter 3	16
TC4 – Timer Counter 4	17
TC5 – Timer Counter 5	18
TC6 – Timer Counter 6	19
TC7 – Timer Counter 7	20
ADC – Analog-to-Digital Converter	21
AC – Analog Comparator	22

Write-protect registers allow the user to disable a selected peripheral's write-protection without doing a read-modify-write operation. These registers are mapped into two I/O memory locations, one for clearing and one for setting the register bits. Writing a one to a bit in the Write Protect Clear register (WPCLR) will clear the corresponding bit in both registers (WPCLR and WPSET) and disable the write-protection for the corresponding peripheral, while writing a one to a bit in the Write Protect Set (WPSET) register will set the corresponding bit in both registers (WPCLR and WPSET) and enable the write-protection for the corresponding peripheral. Both registers (WPCLR and WPSET) will return the same value when read.

If a peripheral is write-protected, and if a write access is performed, data will not be written, and the peripheral will return an access error (CPU exception).

The PAC also offers a safety feature for correct program execution, with a CPU exception generated on double write-protection or double unprotection of a peripheral. If a peripheral *n* is write-protected and a write to one in WPSET[*n*] is detected, the PAC returns an error. This can be used to ensure that the application follows the intended program flow by always following a write-protect with an unprotect, and vice versa. However, in applications where a write-protected peripheral is used in several contexts, e.g., interrupts, care should be taken so that either the interrupt can not happen while the main application or other interrupt levels manipulate the write-protection status, or when the interrupt handler needs to unprotect the peripheral, based on the current protection status, by reading WPSET.

7.7. Register Description

Atomic 8-, 16- and 32-bit accesses are supported. In addition, the 8-bit quarters and 16-bit halves of a 32-bit register, and the 8-bit halves of a 16-bit register can be accessed directly. Refer to the Product Mapping for PAC locations.

Related Links

[Product Mapping](#) on page 19

7.7.1. PAC0 Register Description

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – GCLK

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 2 – SYSCTRL

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 1 – PM

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

7.7.1.2. Write Protect Set

Name: WPSET
Offset: 0x04
Reset: 0x000000
Property: –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								
Bit	23	22	21	20	19	18	17	16
Access								
Reset								
Bit	15	14	13	12	11	10	9	8
Access								
Reset								
Bit	7	6	5	4	3	2	1	0
		EIC	RTC	WDT	GCLK	SYSCTRL	PM	
Access		R/W	R/W	R/W	R/W	R/W	R/W	
Reset		0	0	0	0	0	0	

Bit 6 – EIC

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 5 – RTC

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 4 – WDT

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – GCLK

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 2 – SYSCTRL

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 1 – PM

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

7.7.2. PAC1 Register Description

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 1 – DSU

Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

7.7.3. PAC2 Register Description

8. Packaging Information

8.1. Thermal Considerations

Related Links

[Junction Temperature](#) on page 39

8.1.1. Thermal Resistance Data

The following *table* summarizes the thermal resistance data depending on the package.

Table 8-1. Thermal Resistance Data

Package Type	θ_{JA}	θ_{JC}
32-pin TQFP	68.0°C/W	25.8°C/W
48-pin TQFP	78.8°C/W	12.3°C/W
64-pin TQFP	66.7°C/W	11.9°C/W
32-pin QFN	37.2°C/W	13.1°C/W
48-pin QFN	33.0°C/W	11.4°C/W
64-pin QFN	33.5°C/W	11.2°C/W
64-ball UFBGA	67.4°C/W	12.4°C/W
45-ball WLCSP	37.0°C/W	0.36°C/W

8.1.2. Junction Temperature

The average chip-junction temperature, T_J , in °C can be obtained from the following:

1. $T_J = T_A + (P_D \times \theta_{JA})$
2. $T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$

where:

- θ_{JA} = Package thermal resistance, Junction-to-ambient (°C/W), see Thermal Resistance Data
- θ_{JC} = Package thermal resistance, Junction-to-case thermal resistance (°C/W), see Thermal Resistance Data
- $\theta_{HEATSINK}$ = Thermal resistance (°C/W) specification of the external cooling device
- P_D = Device power consumption (W)
- T_A = Ambient temperature (°C)

From the first equation, the user can derive the estimated lifetime of the chip and decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature T_J in °C.

Related Links

[Thermal Considerations](#) on page 39

8.2. Package Drawings

8.2.1. 64 pin TQFP

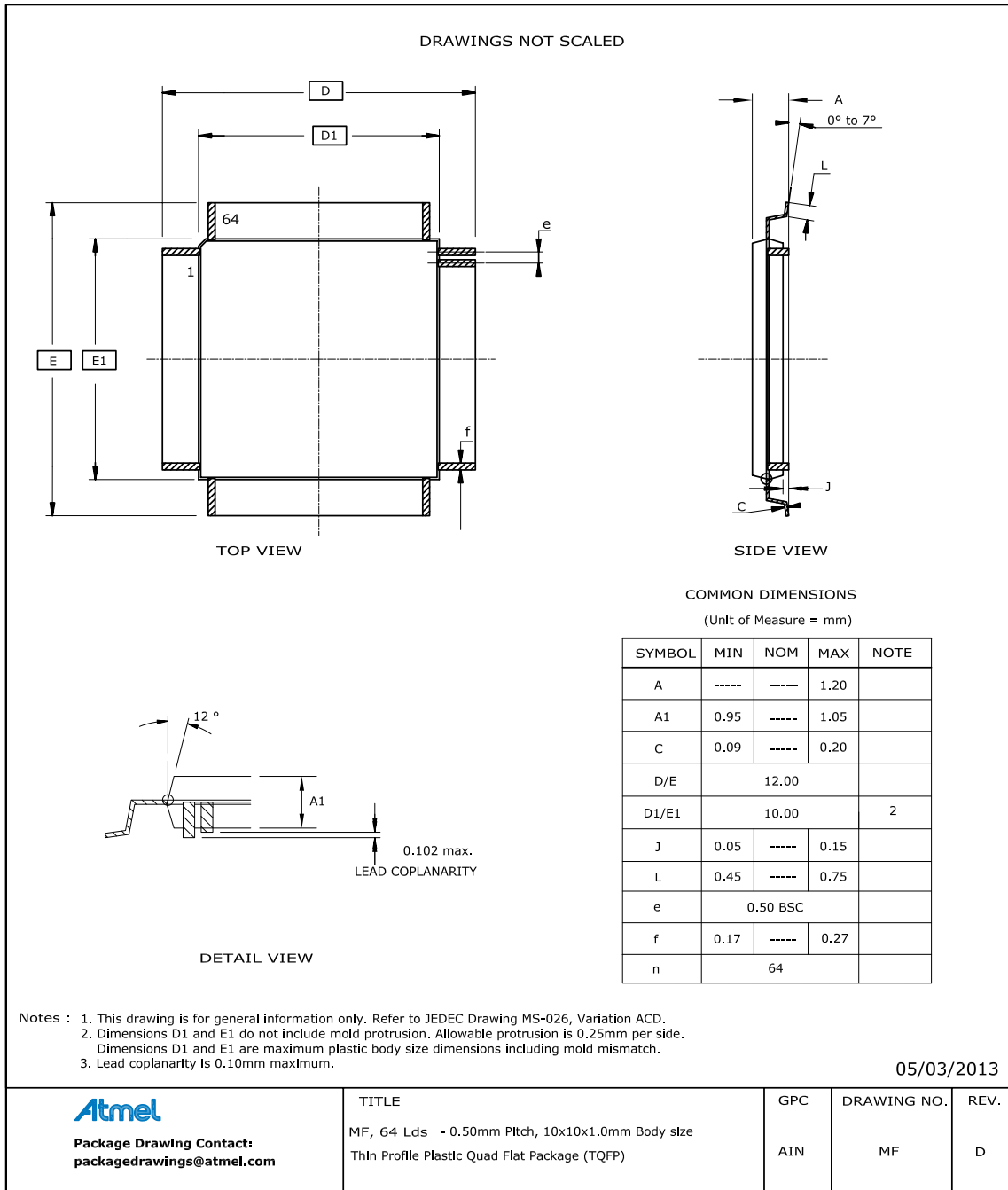


Table 8-2. Device and Package Maximum Weight

300	mg
-----	----

Table 8-3. Package Characteristics

Moisture Sensitivity Level	MSL3
----------------------------	------

Table 8-5. Device and Package Maximum Weight

200	mg
-----	----

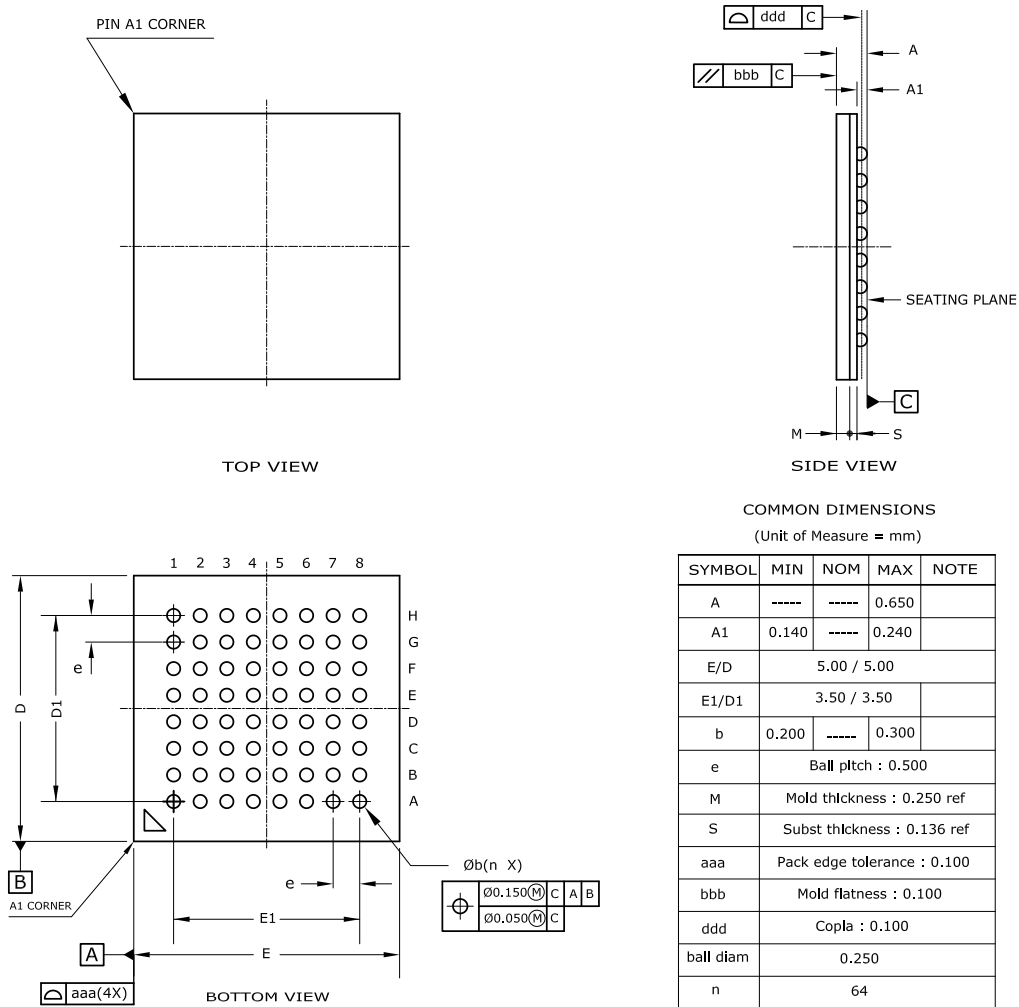
Table 8-6. Package Characteristics

Moisture Sensitivity Level	MSL3
----------------------------	------

Table 8-7. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.3. 64-ball UFBGA



- Notes :
1. This drawing is for general information only. Refer to JEDEC Drawing MO-280, Variation UCCBB for proper dimensions, tolerances, datums, etc.
 2. Array as seen from the bottom of the package.
 3. Dimension A includes stand-off height A1, package body thickness, and lid height, but does not include attached features.
 4. Dimension b is measured at the maximum ball diameter, parallel to primary datum C.

Table 8-8. Device and Package Maximum Weight

27.4	mg
------	----

Table 8-11. Device and Package Maximum Weight

140	mg
-----	----

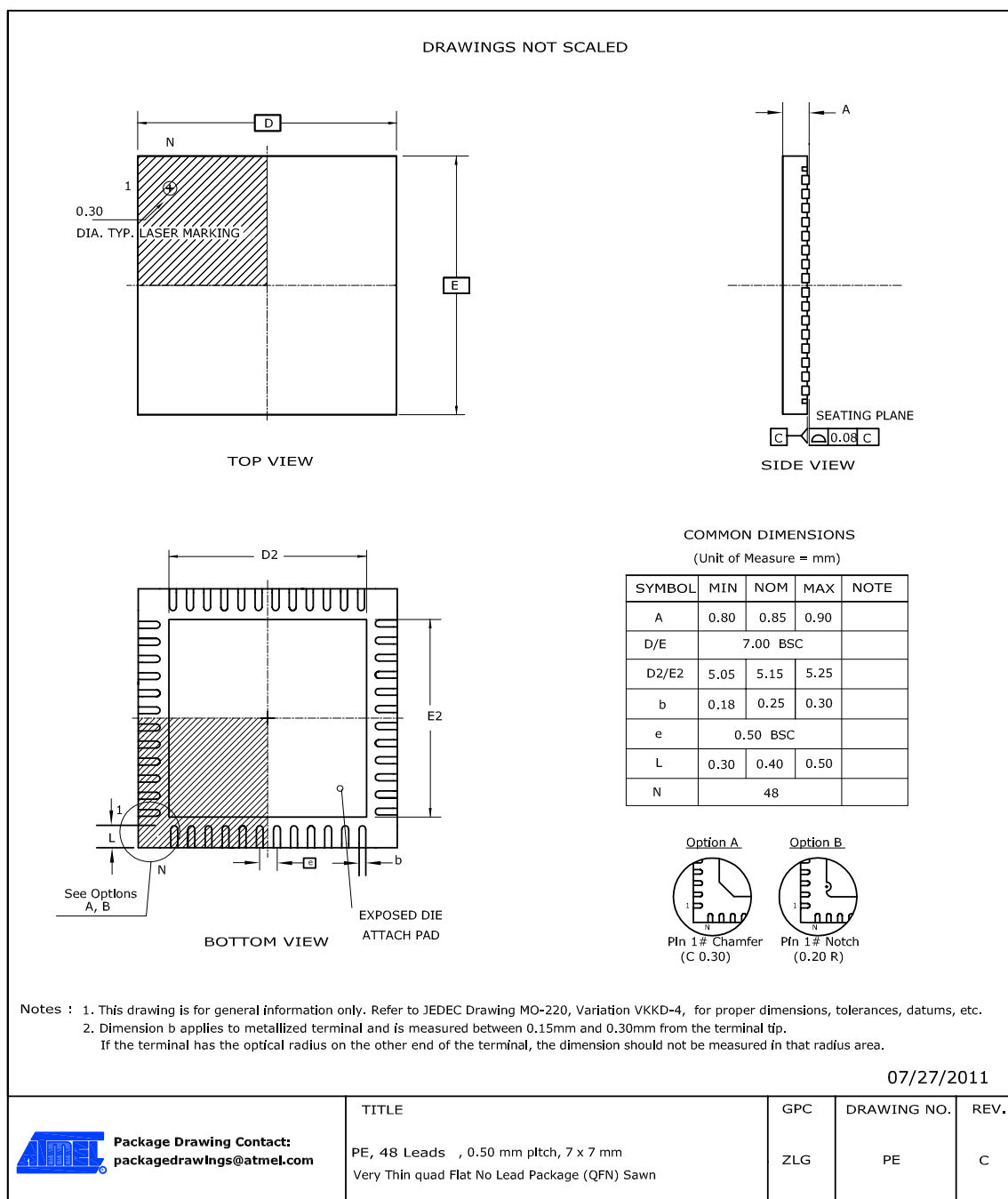
Table 8-12. Package Characteristics

Moisture Sensitivity Level	MSL3
----------------------------	------

Table 8-13. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

8.2.5. 48 pin QFN



Note: The exposed die attach pad is not connected electrically inside the device.

Table 8-14. Device and Package Maximum Weight

140	mg
-----	----

Table 8-15. Package Characteristics

Moisture Sensitivity Level	MSL3
----------------------------	------

Table 8-16. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.6. 45-ball WLCSP

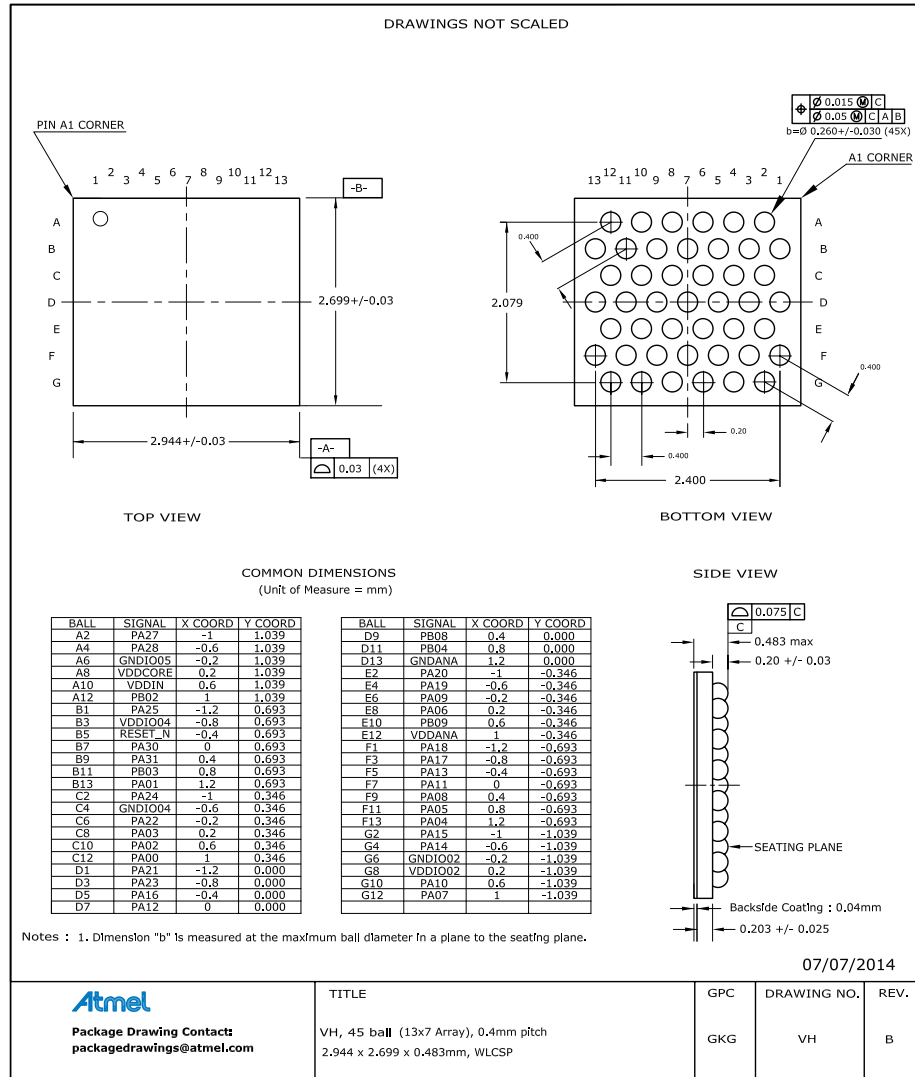


Table 8-17. Device and Package Maximum Weight

7.3	mg
-----	----

Table 8-18. Package Characteristics

Moisture Sensitivity Level	MSL1
----------------------------	------

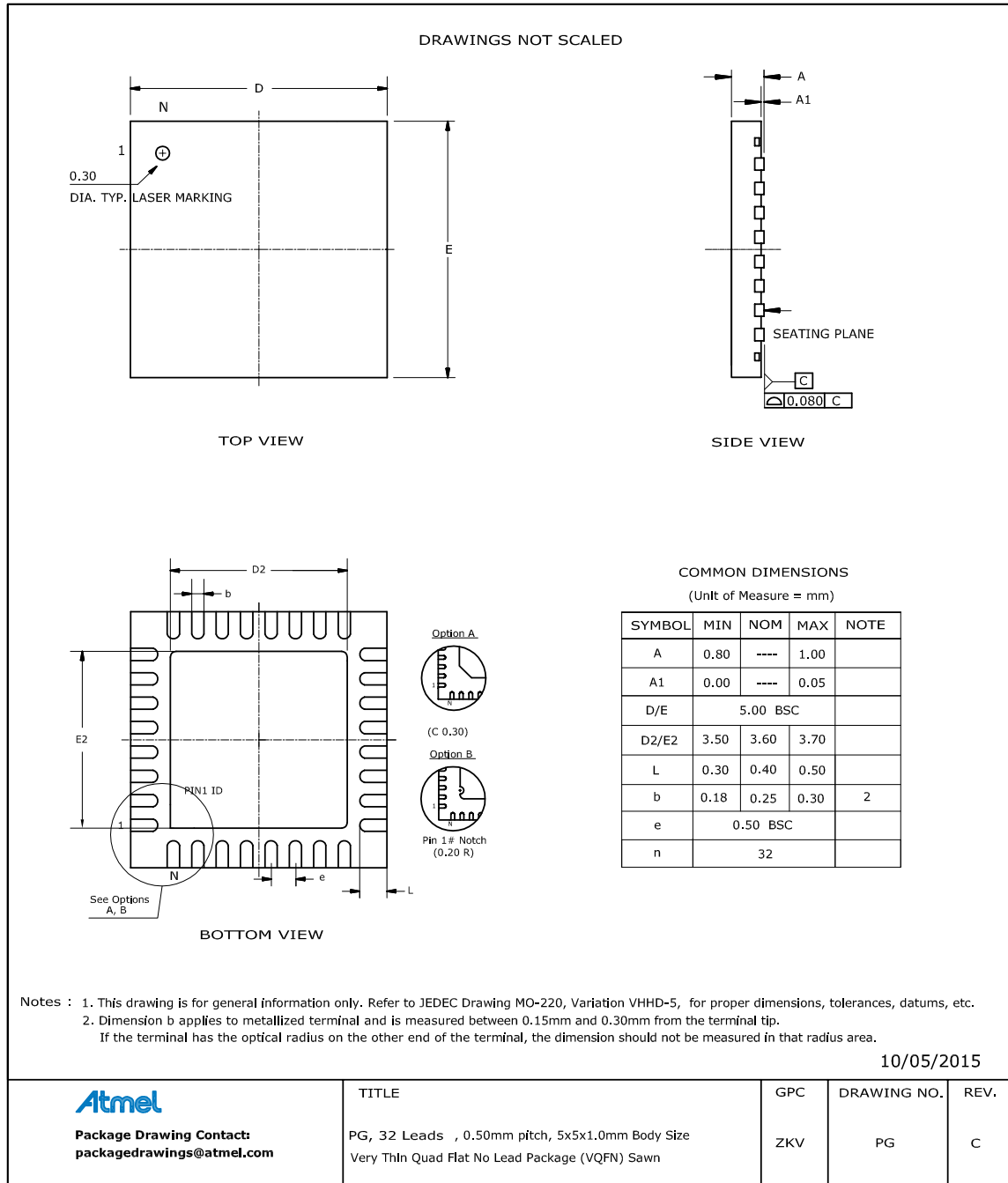
Table 8-19. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E1

Table 8-22. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

8.2.8. 32 pin QFN



Note: The exposed die attach pad is connected inside the device to GND and GNDANA.

Table 8-23. Device and Package Maximum Weight

90	mg
----	----